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Sub: Conflict Minerals--Metals

NIC Components certifies the below referenced conflict minerals, as used in NIC products, do not originate from mines in the Congo and adjoining areas. Metal suppliers, for the referenced conflict metals have provided certifications assuring the metals do not originate from mines in the Congo and adjoining areas.

Conflict metals are generally defined as the following five metals:

- o Gold (Au)
- o Tin (Sn)
- o Tantalum (Ta)
- o Tungsten (W)
- o Cobalt (Co)

NIC Components has identified the below products (passive electronic components) contain the above identified metals:

Gold (Au) ...CAS 7440-57-5:

- Gold wires used on NPC series, SMT Solid Polymer Aluminum Electrolytic Capacitors
- Gold used on fusing element on NFCC series, SMT Chip Fuses
- Gold flash on terminals of NPIS16R & NPIS16W series, SMT Power Inductors
- Gold used on inner electrodes on NRC-S series, Anti-Sulfur SMT Thick Film Chip Resistors
- Gold used in NRD and NSD series, SMT Diodes

Tin (Sn) ... CAS 7440-31-5:

- Industry standard matte Sn finish or Sn blend finish on component terminals
 - SMT & LDD Capacitors:
 - Aluminum Electrolytic Capacitors
 - Ceramic (MLCC) Capacitors
 - Double Layer Capacitors
 - Film Capacitors
 - Tantalum Electrolytic Capacitors
 - SMT & LDD Resistors; Thick Film & Thin Film
 - SMT Inductors; Chip and Power & SMT Ferrite Chip Beads
 - SMT Varistors & Chip Fuses

Tantalum (Ta) ... CAS 7440-25-7:

- Tantalum Electrolytic Capacitors; NDTM, NTC-L, NTC-T and NTP series

No **Tungsten (W)** nor **Cobalt (Co)** are used in NIC Components products

Prepared by:

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A handwritten signature in black ink, appearing to read 'Jim Wright', with a horizontal line extending to the right.